PCN Number: 202		202	0200331001.1			PCN Date:		e:	April 1, 2020		
Title: Qualification of MII			HO8 as an additional Fab site option for select devices								
Cus	stomer	Contact:		PC	CN	Manager		Dept:			Quality Services
Proposed 1 st Ship Date:				July 2, 2020 Estimate Availabi		ited Sample bility:		ole	Date provided at sample request.		
Cha	ange Ty	уре:									
Assembly Site					Assembly Process			1	Assembly Materials		
Design					Electrical Specification				Mechanical Specification		
Test Site				Packing/Shipping/Labeling				•	Test Process		
Wafer Bump Site				Wafer Bump Material				١	Wafer Bump Process		
				₩ Wafer Fab Materials				1	Wafer Fab Process		
				Part number change							
	PCN Details										
Des	Description of Change:										
	Texas Instruments is pleased to announce the qualification of its MIHO8 fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.										

С	urrent Fab Site	9	Additional Fab Site			
Current Fab Site	Process	Wafer Diameter	Additional Site	Process	Wafer Diameter	
RFAB	LBC7	300 mm	MIHO8	LBC7	200 mm	

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current:

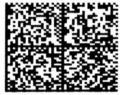
Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson

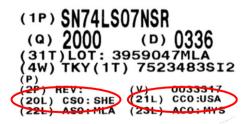
New Fab Site:

MIHO8	MH8	JPN	Ibaraki
New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City

Sample product shipping label (not actual product label)







Product Affected:

BQ24780SRUYR	SN2850RUYR	SN2867RUYR	SN2867RUYT
BQ24780SRUYT	SN2850RUYT		

Qualification Report

Approve Date 27-Mar-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: BQ24780SRUY	QBS Product Reference: BQ24780SRUY	QBS Process Reference: <u>TPS62110RSA</u>	QBS Package Reference: 430F2132IRHBR	QBS Package Reference: TPS51285BRUKR
HTOL	Life Test, 140C	480 Hours	-	-	3/231/0	-	-
ELFR	Early Life Failure Rate, 140C	48 Hours	-	-	3/1881/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0		
AC	Autoclave 121C	96 Hours	-	1/77/0	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	1/77/0	3/231/0	3/231/0	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	-
CDM	ESD - CDM	1500 V	1/3/0	-	-	-	-
HBM	ESD - HBM	4000 V	1/3/0	-	-	-	-
LU	Latch-up	(per JESD78)	1/6/0	•	3/15/0	•	-

- QBS: Qual By Similarity
- Qual Device BQ24780SRUY is qualified at LEVEL 2-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1kHours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47:-55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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